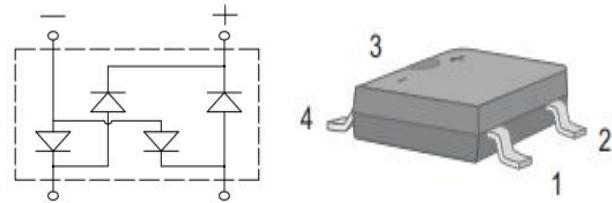


Bridge Rectifier Diode 整流桥**■Features 特点**

Glass passivated chip junction 玻璃钝化结
 High surge current capability 高浪涌电流能力
 Reflow Solder Temperature 220°C 回流焊温度 220 度
 Package 封装: MBF

**■Maximum Rating 最大额定值**

(TA=25°C unless otherwise noted 如无特殊说明, 温度为 25°C)

Characteristic 特性参数	Symbol 符号	MB12F	MB14F	MB16F	MB18F	MB110F	MB115F	MB120F	Unit 单位
Peak Reverse Voltage 反向峰值电压	V _{RRM}	20	40	60	80	100	150	200	V
DC Reverse Voltage 直流反向电压	V _{R(DC)}	20	40	60	80	100	150	200	V
RMS Reverse Voltage 反向电压均方根值	V _{R(RMS)}	14	28	42	56	70	105	140	V
Forward Rectified Current 正向整流电流	I _F	1							A
Peak Surge Current 峰值浪涌电流	I _{FSM}	30							A
Thermal Resistance J-A 结到环境热阻	R _{θJA}	100							°C/W
Junction Temperature 结温	T _J	150							°C
Storage Temperature 储藏温度	T _{stg}	-55 to +150 °C							

■Electrical Characteristics 电特性

(TA=25°C unless otherwise noted 如无特殊说明, 温度为 25°C)

Characteristic 特性参数	Symbol 符号	MB12F- MB14F	MB16F	MB18F- MB110F	MB115F- MB120F	Unit 单位	Condition 测试条件
Forward Voltage 正向电压降	V _F	0.55	0.7	0.85	0.9	V	I _F =1A
Reverse Current (T _A =25°C) 反向漏电流(T _A =125°C)	I _R	300 10000		200 5000	100 2000	uA	V _R =V _{RRM}
Diode Capacitance 二极管电容	C _D	13				pF	V _R =4V, f=1MHz

■Typical Characteristic Curve 典型特性曲线

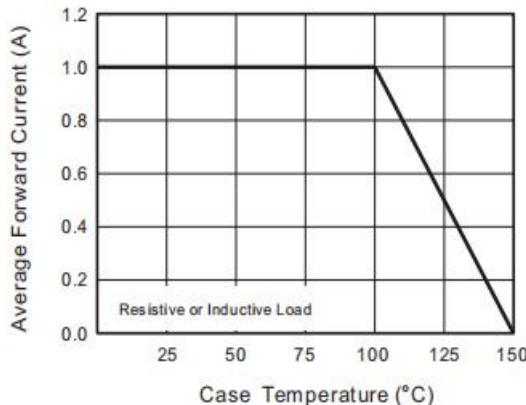


Figure 1: Forward Current Derating Curve

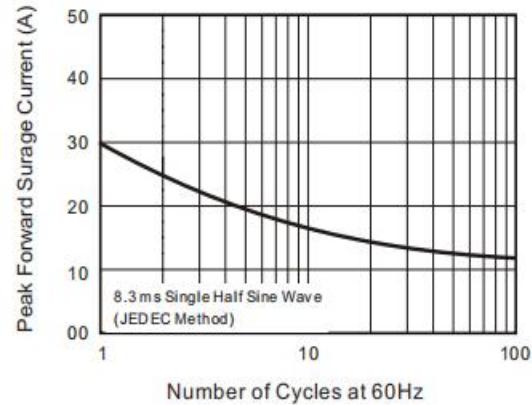


Figure 2: Peak Forward Surge Current

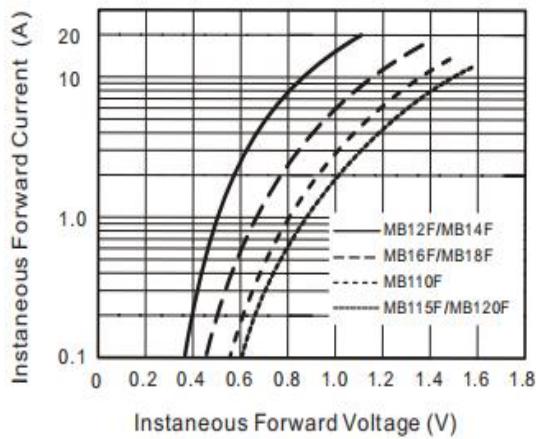


Figure 3: Instantaneous Forward Characteristics

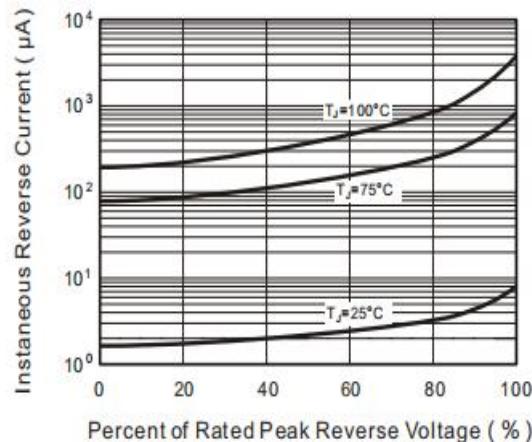


Figure 4: Reverse Leakage Characteristics

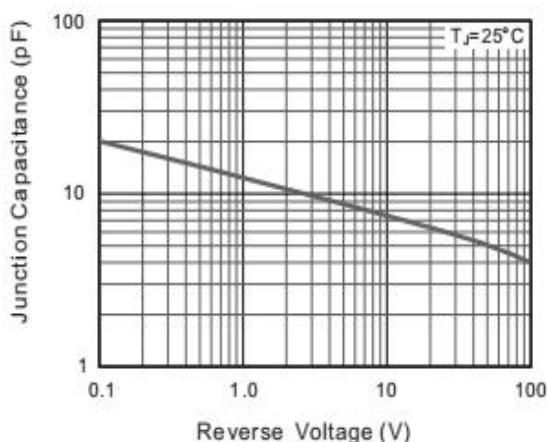


Figure 5: Junction Capacitance Characteristics

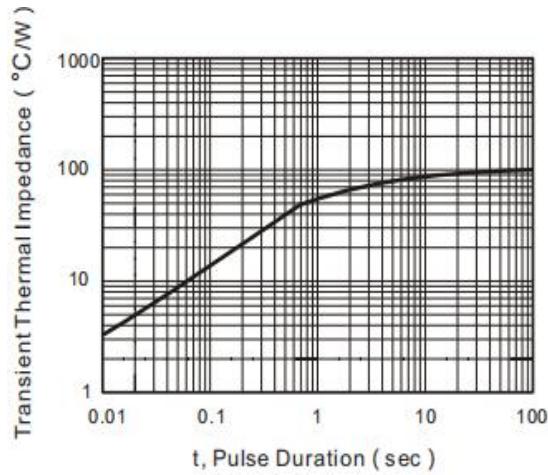
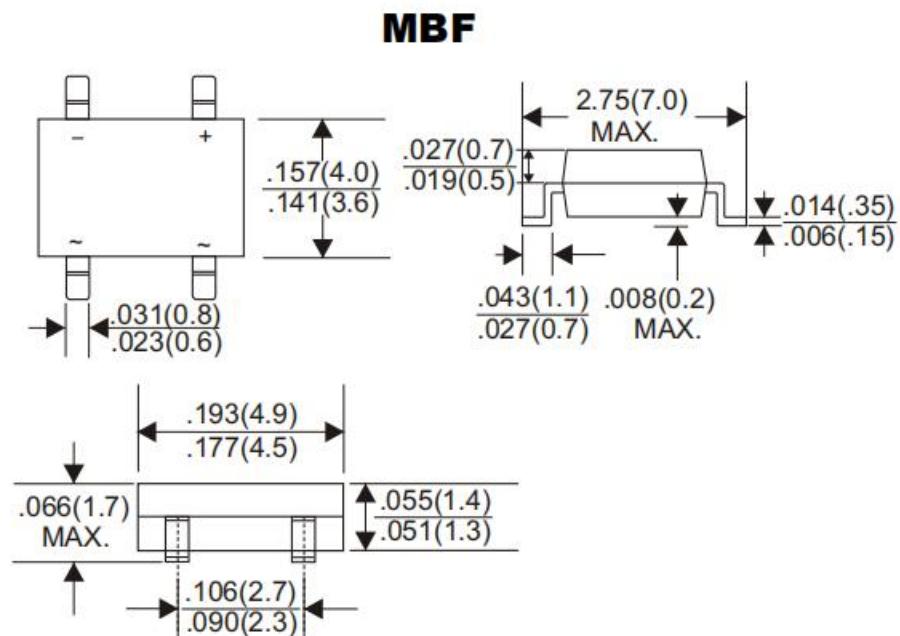


Figure 6: Transient Thermal Impedance

■ Dimension 外形封装尺寸



Dimensions in inches and (millimeters)